

WEICON C



0,2 kg

0,5 kg



2,0 kg

flowable
aluminium-filled
temperature-resistant up to 220 °C (428 °F)

ISSA-Code 75.509.07/08

IMPA-Code 812903/04

WEICON C is a temperature-resistant and flowable epoxy resin system especially for industrial use. The adhesive is non-corrosive, anti-magnetic and cures practically without shrinkage.

WEICON C is particularly suitable as an adhesive for large-surface applications, for the casting of moulds, and for the production of fixing devices and tools (e.g. injection moulds). It can be used in tool and mould making as well as in many other industrial areas, which are exposed to high thermal stress.

Characteristics

Base	epoxy
Filler	aluminium
Texture	flowable
Colour after curing	grey

Processing

Processing temperature	+15 °C up to +40 °C
Component temperature	> 3 °C over dew point
Relative air humidity	max. 85 %
Mixing ratio by weight	100:8
Mixing ratio by volume	100:14
Viscosity of the mixture at 25 °C and 20 1/s	25,000 mPa·s
Density of the mixture	1.6 g/cm ³
Consumption at layer thickness of 1.0 mm	1.6 g/cm ²
Max. layer thickness per work step	60 mm

Curing

Pot life at 20 °C, 500g batch	60 min.
Repeated application possible after (35 % strength)	8 h
Capable of bearing mechanical loads (80 % strength)	10 h
Final strength after (100 % strength)	24 h
Shrinkage	0.10 %

Mechanical properties after curing

Tensile strength	DIN EN ISO 527-2	48 MPa
Elongation at break (tensile)	DIN EN ISO 527-2	0.9 %
E-modulus (tensile)	DIN EN ISO 527-2	6700-6900 MPa
Compressive strength	DIN EN ISO 604	140 MPa
E-modulus (pressure)	DIN EN ISO 604	5600-6000 MPa
Bending strength	DIN EN ISO 178	77 MPa
Impact strength	DIN EN ISO 179-1/1eU	8-9 kJ/m ²
Hardness (Shore D)	DIN ISO 7619	84±3
Adhesive strength	DIN EN ISO 4624	16 MPa
Lap shear strength material thicken. 1.5mm	DIN EN 1465	
Steel 1.0338 sandblasted		11 MPa
Stainless steel V2A sandblasted		10 MPa
Aluminium sandblasted		6 MPa
Galvanized steel		5 MPa

Thermal parameters

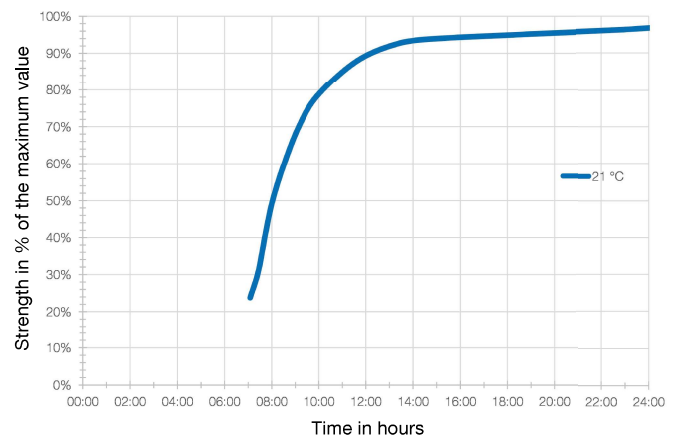
Temperature resistance		-35 °C bis +220 °C
Tg after curing at room temperature	(DSC)	approx. +61 °C
Tg after tempering (at 120 °C)	(DSC)	+130 °C
Heat deflection temperature	DIN EN ISO 75-2 (B)	+60 °C/+130 °C*
Thermal conductivity	DIN EN ISO 22007-4	0.6 W/m·K
Heat capacity	DIN EN ISO 22007-4	0.90 J/(g·K)

Electrical parameters

Resistivity	DIN IEC93	5.0·10 ¹² Ωm
Magnetic		no

* after tempering (detailed information see curing)

Increase in strength



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Instructions for use

When using WEICON products, the physical, safety-related, toxicological and ecological data and regulations in our EC safety data sheets (www.weicon.com) must be observed.



Surface pre-treatment

The successful application of WEICON C depends on the thorough preparation of the surfaces. This is the most important factor for overall success. Dust, dirt, oil, grease, rust and moisture or wetness have a negative impact on the adhesion. Therefore, before processing WEICON C, the following points must be observed:

The areas to be bonded or repaired must be free of any oil, grease, dirt, rust, oxides, paint and other impurities or residues. For cleaning and degreasing, we recommend WEICON Cleaner Spray S.

Smooth and particularly heavily soiled surfaces should additionally be treated by mechanical surface pre-treatment, e.g. by grinding or preferably by blasting. In case of blasting, the surface should be brought to a degree of purity of SA 2 1/2 - "Near White Blast Cleaning" (according to ISO 8501/1-2, NACE, SSPC, SIS). In order to achieve an optimum surface roughness of 75 - 100 µm, angular, disposable blasting media (aluminum oxide, corundum) should be used. The surface quality is negatively influenced by the use of reusable blasting media (slag, glass, quartz) but also by ice blasting. The air for blasting must be dry and oil-free.

Metal parts that have come into contact with sea water or other salt solutions should first be rinsed thoroughly with demineralised water and, if possible, left to rest overnight so that all salts can be dissolved from the metal. Before each application of WEICON C, a test for soluble salts should be carried out according to the Bresle method (DIN EN ISO 8502-6).

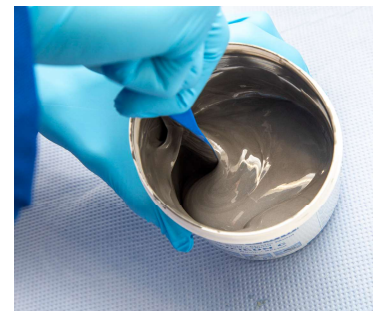
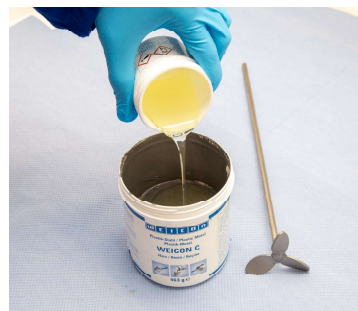
The maximum amount of soluble salts remaining on the substrate should not exceed 40 mg/m². Heating and repeated blasting of the surface may be necessary to remove all soluble salts and moisture.

After each mechanical pre-treatment, the surface should be cleaned again with WEICON Cleaner Spray S and protected from further contamination until the coating is applied. Areas where no adhesion to the substrate is desired must be treated with silicone-free mould release agents. For smooth surfaces, we recommend WEICON Mould Release Agent Liquid F 1000 or, for porous surfaces, WEICON Mould Release Agent Wax P 500.

After the surface pre-treatment, WEICON C should be applied as soon as possible (within one hour) to avoid oxidation, flash rust or new contamination.

Mixing

Before adding the hardener, the resin and its fillers must be stirred thoroughly and free of bubbles. Then mix the resin and the hardener thoroughly for at least four minutes at 20°C (68°F). To do so, use the included processing spatula or a mechanical mixer, such as the Stirrer Stainless Steel. With mechanical mixers, a low speed of max. 500 rpm should be used. The components should be stirred until a homogeneous mixture is achieved. The mixing ratio of the two components must be strictly observed, as otherwise, strongly deviating physical values will result (max. deviation +/- 2%). Only mix a batch as large as can be processed within the pot life of 60 minutes. The specified pot life refers to a material batch of 500 g and 20°C (68°F) material temperature. Mixing larger quantities or higher processing temperatures will result in faster curing due to the typical reaction heat of epoxy resins.



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Application

For processing, we recommend an ambient temperature of 20°C (68°F) at less than 85% relative humidity. The highest adhesive strength is achieved when the parts to be processed are heated to >35°C (>95°F) before application. For a thin pre-coat, work WEICON C intensively into the surface in crosswise layers using the Contour Spatula Flexy or a paint brush to achieve maximum adhesion. By means of this technique, the epoxy resin penetrates well into all cracks and roughness depths. Afterwards, further applications can be carried out straight away, until the desired layer thickness is reached. Make sure that the epoxy resin is applied evenly and without air bubbles.

Curing

Final hardness is reached after 24 hours at 20°C (68°F) at the latest. At lower temperatures, the curing can be accelerated by evenly applying heat up to max. 40°C (104°F), e.g. with a heating pack, hot air blower or fan heater. Higher temperatures shorten the curing time.

The following rule of thumb applies: Each increase by +10°C (50°F) above room temperature (20°C/68°F) will decrease the curing time by half. Temperatures below 16°C (61°F) increase the curing time, until at approx. 5°C (41°F) and below, almost no reaction will take place at all. In order to achieve a permanently high temperature resistance, after 48 hours, tempering should be carried out as follows:

2 h at +40°C, 2 h at +60°C, 2 h at +80°C, 2 h at +100°C, finally 14 h at +120°C.

Storage

Store WEICON C at room temperature in a dry place. Unopened containers can be stored at temperatures of +18°C to +28°C for at least 24 months after delivery date. Unopened containers must be used up within 6 months.

Scope of delivery

- 10953001 Processing Spatula, short (0.2 kg, 0.5 kg package)
 - 10953003 Processing Spatula, long (2.0 kg package)
 - 10953020 Contour Spatula Flexy
 - 10953015 Protective Gloves
- Instructions for use

Accessories

- 11202500 Cleaner Spray S, spray can 500 ml
- 15200005 Cleaner S, canister 5 l
- 11207400 Surface Cleaner, spray can 400 ml
- 15207005 Surface Cleaner, canister 5 l
- 10604025 Mould Release Agent Liquid F 1000, 250 ml
- 10604515 Mould Release Agent Wax P 500, 150 g
- 10539115 Repair Stick Multi-Purpose 115 g
- 10850005 Glass Fibre Cloth Tape, 50 mm x 1 m
- 10953001 Processing Spatula, short
- 10953003 Processing Spatula, long
- 10953010 Stirrer Stainless Steel
- 15841500 Pump-Dispenser WPS 1500
- 13955001 Cartridge 310 ml empty
- 13250001 Cartridge Gun
- 52000035 Cable Scissors No. 35
- 10851010 Processing-Kit

Recommended tools

- Angle grinder
- Blast machine
- Heating pack, hot air blower or fan heater
- Smoothing trowel, spatula
- PE foil 0.2 mm
- Fabric tape
- Paint brush, foam roller
- Lint-free cloths

Available sizes

- 10100002 WEICON C 0,2 kg
- 10100005 WEICON C 0,5 kg
- 10100020 WEICON C 2,0 kg

Conversion table

- (°C x 1.8) + 32 = °F
- mm/25.4 = inch
- µm/25.4 = mil
- N x 0.225 = lb
- N/mm² x 145 = psi
- MPa x 145 = psi
- Nm x 8.851 = lb·in
- Nm x 0.738 = lb·ft
- Nm x 141.62 = oz·in
- mPa·s = cP
- N/cm x 0.571 = lb/in
- kV/mm x 25.4 = V/mil

	WEICON A	WEICON B	WEICON BR	WEICON C	WEICON F	WEICON FZ	WEICON HB 300	WEICON Ceramic BL	WEICON GL	WEICON Ceramic W	WEICON SF	WEICON ST	WEICON HP	WEICON TI	WEICON UW	WEICON WP	WEICON WR	WEICON WR2	WEICON CBC
Repair and moulding	X	X	X	X	X	X	X				X	X		X	X			X	
Adhesive				X									X		X				
Wear protection								X	X	X						X			
Potting and gap filling	X					X											X	X	X

www.weicon.de/products


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Chemical resistance of WEICON Plastic Metals after curing*

Acetic acid dilute < 5%	+	Hydrocarbons, aliphatic (crude oil derivatives)	+
Acetone	0	Hydrocarbons, aromatic (benzene, toluene, xylene)	-
Alkalis (basic materials)	+	Hydrochloric acid < 10%	+
Amyl acetate	+	Hydrochloric acid 10 - 20%	+
Amyl alcohols	+	Hydrofluoric acid dilute	0
Anhydrous ammonia 25%	+	Hydrogen peroxide < 30% (hydrogen superoxide)	+
Barium hydroxide	+	Impregnating oils	+
Butyl acetate	+	Magnesium hydroxide	+
Butyl alcohol	+	Maleic acid (cis-butenedioic acid)	+
Calcium hydroxide (slaked lime)	+	Methanol (methyl alcohol) < 85%	0
Carbolic acid (phenol)	-	Milk of lime	+
Carbon disulphide	+	Naphthalene	-
Carbon tetrachloride (tetrachloromethane)	+	Naphthene	-
Caustic potash solution	+	Nitric acid < 5%	0
Chlorinated water	+	Oils, minerals	+
Chloroacetic acid	-	Oils, vegetable and animal	+
Chloroform (trichloromethane)	0	Oxalic acid < 25% (ethanedioic acid)	+
Chlorosulphonic acid	-	Paraffin	+
Chromic acid	+	Perchloroethylene	0
Chroming baths	+	Petrol (92 - 100 octane)	+
Creosote oil	-	Phosphoric acid < 5%	+
Cresylic acid	-	Phthalic acid, phthalic acid anhydride	+
Crude oil	+	Potassium carbonate (potash solution)	+
Crude oil and crude oil products	+	Potassium hydroxide (caustic potash) 0-20%	+
Diesel fuel oil	+	Soda lye	+
Ethanol < 85% (ethyl alcohol)	0	Sodium bicarbonate (sodium hydrogen carbonate)	+
Ethyl alcohol	0	Sodium carbonate (soda)	+
Ethyl benzole	-	Sodium chloride (cooking salt)	+
Ethyl ether	+	Sodium hydroxide < 20% (caustic soda)	0
Exhaust gases	+	Sulphur dioxide	+
Formic acid >10%	-	Sulphuric acid < 5%	0
Glycerine (trihydroxypropane)	+	Tannic acid dilute < 7%	+
Glycol	0	Tetralin (tetrahydronaphthalene)	0
Grease, oils and waxes	+	Toluene	-
Heating oil, diesel	+	Trichloroethylene	0
Humic acid	+	Turpentine substitute (white spirit)	+
Hydrobromic acid < 10%	+	Xylene	-

+ = resistant 0 = resistant for a limited time - = not resistant

* Storage of all WEICON Plastic Metals was at +20°C chemical temperature

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